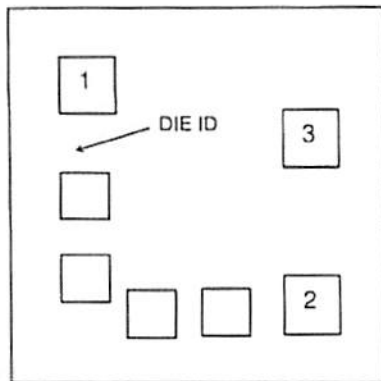




# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD	FUNCTION
1	CATHODE
2	ANODE
3	REF

Top Material: Al  
 Backside Material: Si  
 Bond Pad Size: .0354 X .0354"  
 Backside Potential: ANODE OR OPEN  
 Mask Ref: TLV431

APPROVED BY: DK

DIE SIZE .024" X .024"

DATE: 8/30/23

MFG: TEXAS INSTRUMENTS

THICKNESS .000"

P/N: TLV431